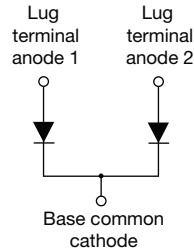


HEXFRED®

Ultrafast Soft Recovery Diode, 210 A


TO-244

FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced snubbing

DESCRIPTION / APPLICATIONS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

| PRIMARY CHARACTERISTICS | |
|-------------------------|---------------------------|
| $I_{F(AV)}$ | 210 A |
| V_R | 600 V |
| $I_{F(DC)}$ at T_C | 120 A at 100 °C |
| Package | TO-244 |
| Circuit configuration | Two diodes common cathode |

| ABSOLUTE MAXIMUM RATINGS | | | | |
|--|----------------|--|-------------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS |
| Cathode to anode voltage | V_R | | 600 | V |
| Continuous forward current | I_F | $T_C = 25\text{ °C}$ | 235 | A |
| | | $T_C = 100\text{ °C}$ | 120 | |
| Single pulse forward current | I_{FSM} | Limited by junction temperature | 600 | |
| Non-repetitive avalanche energy | E_{AS} | $L = 100\text{ }\mu\text{H}$, duty cycle limited by maximum T_J | 2.2 | mJ |
| Maximum power dissipation | P_D | $T_C = 25\text{ °C}$ | 463 | W |
| | | $T_C = 100\text{ °C}$ | 185 | |
| Operating junction and storage temperature range | T_J, T_{Stg} | | -55 to +150 | °C |

| ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25\text{ °C}$ unless otherwise specified) | | | | | | | |
|--|----------|---|------------|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNITS |
| Cathode to anode breakdown voltage | V_{BR} | $I_R = 100\text{ }\mu\text{A}$ | | 600 | - | - | V |
| Maximum forward voltage | V_{FM} | $I_F = 105\text{ A}$ | See fig. 1 | - | 1.38 | 1.9 | |
| | | $I_F = 210\text{ A}$ | | - | 1.6 | 2.25 | |
| | | $I_F = 105\text{ A}, T_J = 125\text{ °C}$ | | - | 1.3 | 1.56 | |
| Maximum reverse leakage current | I_{RM} | $T_J = 125\text{ °C}, V_R = 480\text{ V}$ | See fig. 2 | - | 1.8 | 6.0 | mA |
| Junction capacitance | C_T | $V_R = 200\text{ V}$ | See fig. 3 | - | 200 | 300 | pF |
| Series inductance | L_S | From top of terminal hole to mounting plane | | - | 6.0 | - | nH |



| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | |
|--|--------------------------|---|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Reverse recovery time (fig. 5) | t _{rr} | I _F = 1.0 A, dI _F /dt = 200 A/μs, V _R = 30 V | - | 35 | - | ns |
| | | T _J = 25 °C | - | 90 | 140 | |
| | | T _J = 125 °C | - | 160 | 240 | |
| Peak recovery current (fig. 6) | I _R RM | T _J = 25 °C | - | 10 | 18 | A |
| | | T _J = 125 °C | - | 15 | 30 | |
| Reverse recovery charge (fig. 7) | Q _{rr} | T _J = 25 °C | - | 450 | 1300 | nC |
| | | T _J = 125 °C | - | 1200 | 3600 | |
| Peak rate of recovery current (fig. 8) | dI _{(rec)M} /dt | T _J = 25 °C | - | 310 | - | A/μs |
| | | T _J = 125 °C | - | 240 | - | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | |
|--|-----------------------------------|------------|------|----------|---------------------|-------------|
| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNITS | |
| Maximum junction and storage temperature range | T _J , T _{Stg} | -55 | - | 150 | °C | |
| Thermal resistance, junction to case | R _{thJC} | per leg | - | - | 0.27 | °C/W K/W |
| | | per module | - | - | 0.135 | |
| Typical thermal resistance, case to heatsink | R _{thCS} | - | 0.10 | - | | |
| Weight | | - | 68 | - | g | |
| | | - | 2.4 | - | oz. | |
| Mounting torque ⁽¹⁾ | | 30 (3.4) | - | 40 (4.6) | lbf · in (N · m) | |
| Mounting torque center hole | | 12 (1.4) | - | 18 (2.1) | | |
| Terminal torque | | 30 (3.4) | - | 40 (4.6) | | |
| Vertical pull | | - | - | 80 | lbf · in | |
| 2" lever pull | | - | - | 35 | | |

Note

- (1) Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached

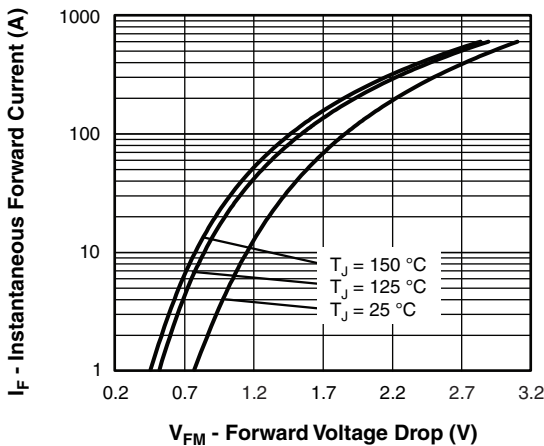


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

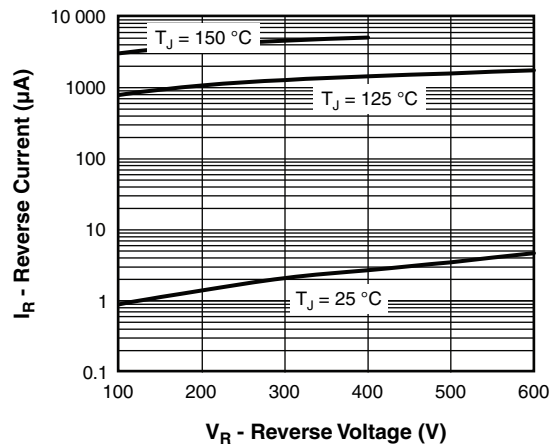


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

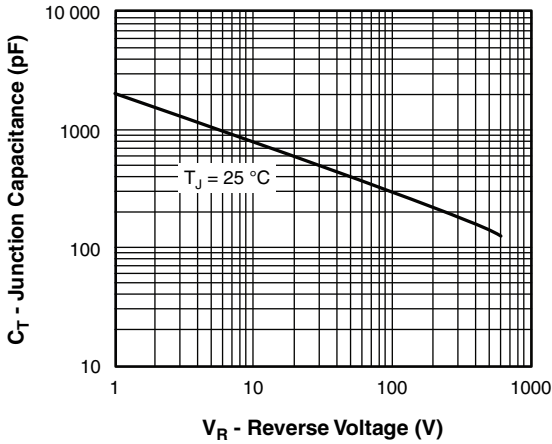


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

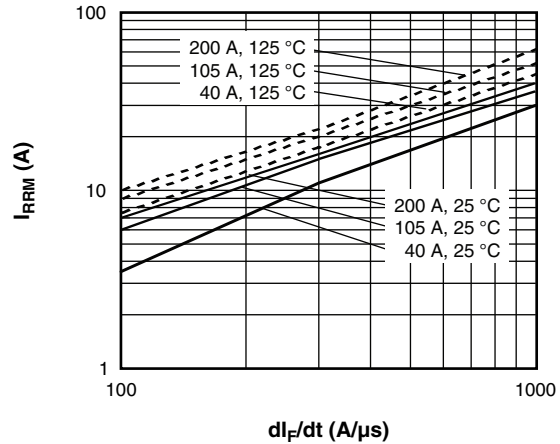


Fig. 6 - Typical Recovery Current vs. dI_F/dt (Per Leg)

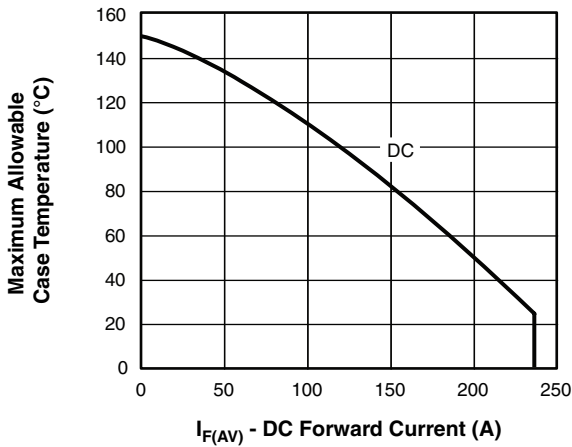


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

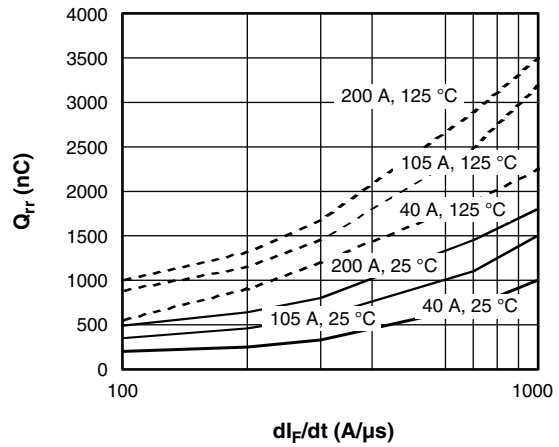


Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)

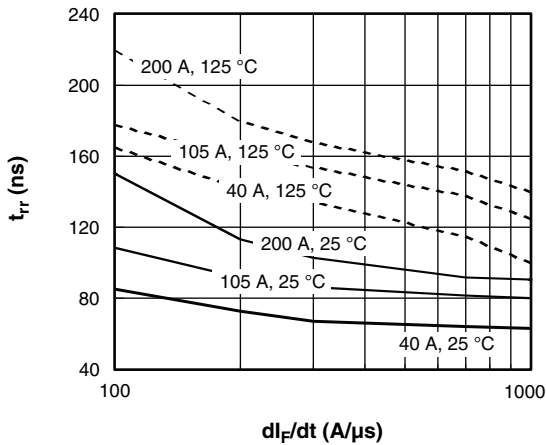


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt (Per Leg)

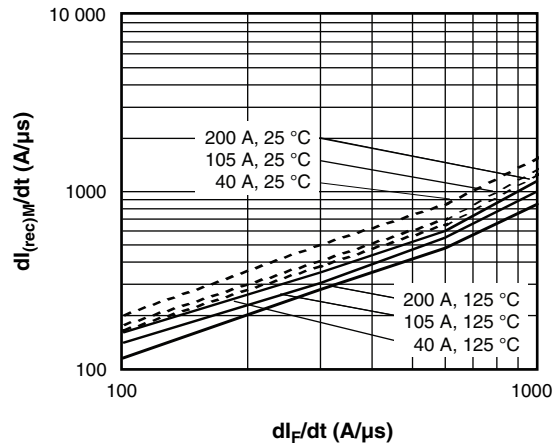


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)

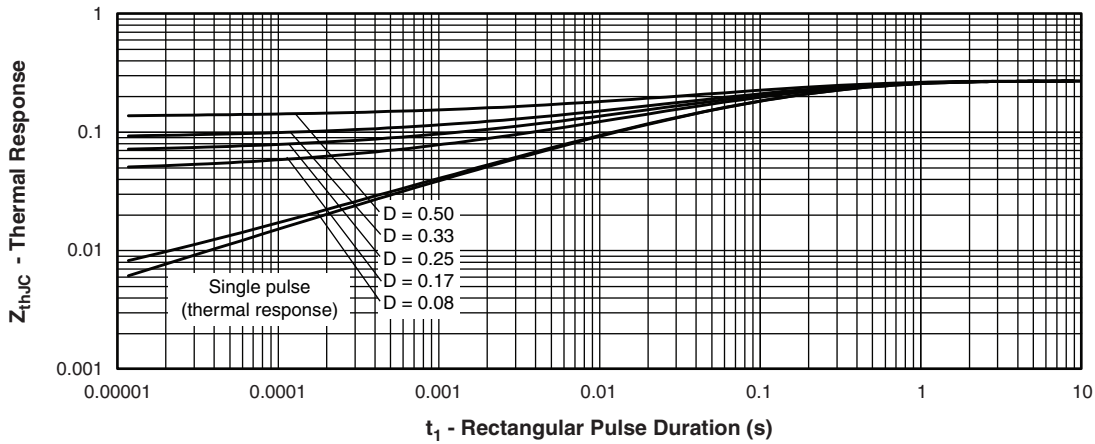


Fig. 9 - - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

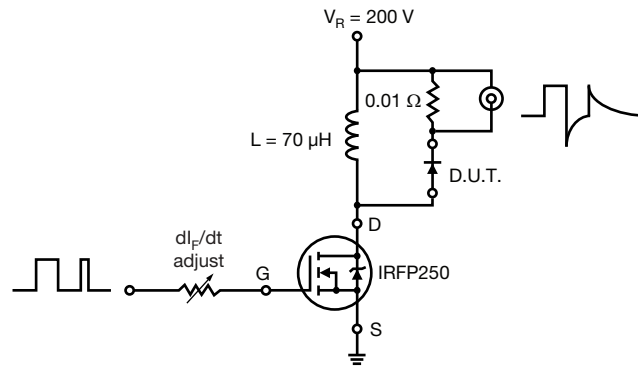


Fig. 10 - - Reverse Recovery Parameter Test Circuit

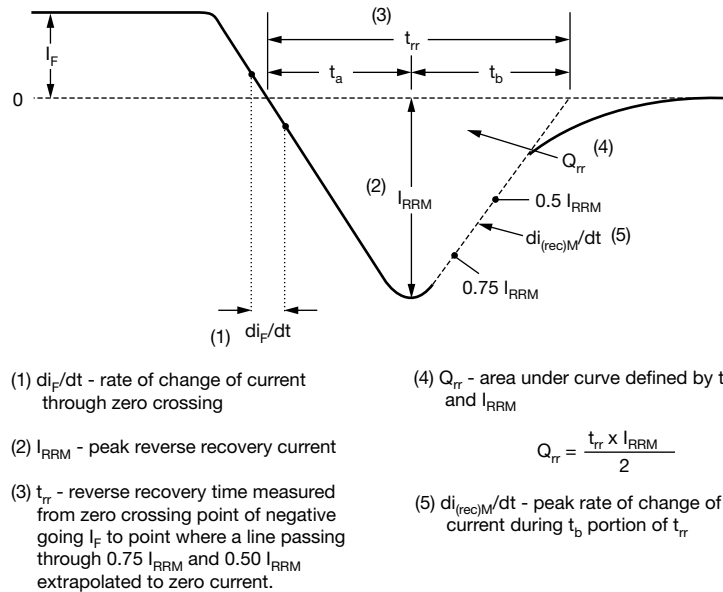


Fig. 11 - Reverse Recovery Waveform and Definitions

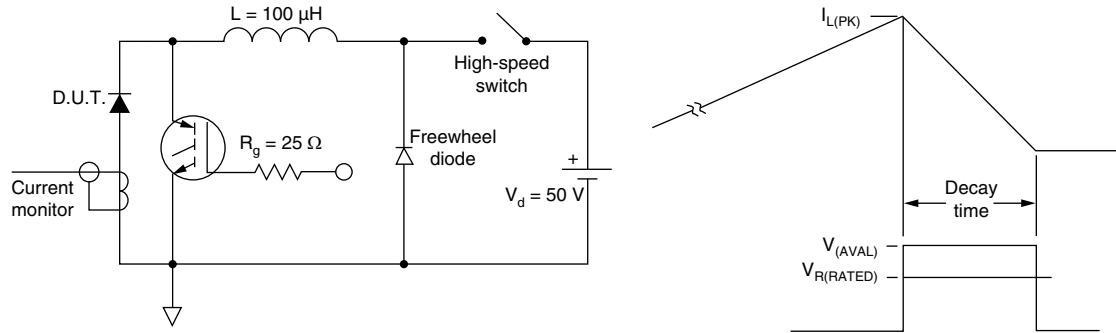


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

| | | | | | | | |
|-------------|------------|------------|------------|-----------|-----------|----------|------------|
| Device code | VS- | HFA | 210 | NJ | 60 | C | PbF |
| | ① | ② | ③ | ④ | ⑤ | ⑥ | ⑦ |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 |
| | - | - | - | - | - | - | - |
| | - | - | - | - | - | - | - |
| | - | - | - | - | - | - | - |
| | - | - | - | - | - | - | - |
| | - | - | - | - | - | - | - |
| | - | - | - | - | - | - | - |
| | - | - | - | - | - | - | - |

- 1 - Vishay Semiconductors product
- 2 - HEXFRED® family, electron irradiated
- 3 - Average current rating
- 4 - NJ = TO-244
- 5 - Voltage rating (60 = 600 V)
- 6 - C = two diodes common cathode
- 7 - Lead (Pb)-free

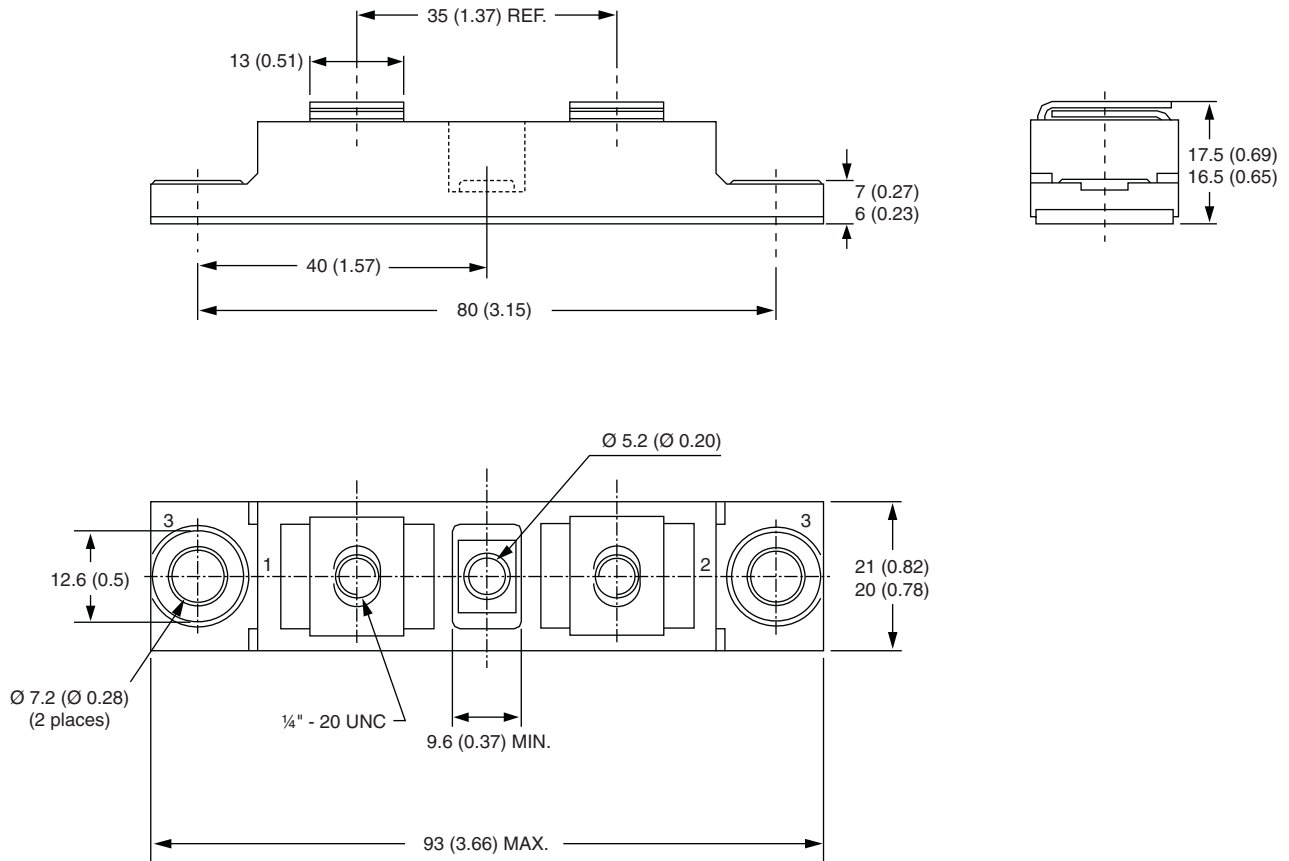
LINKS TO RELATED DOCUMENTS

| | |
|------------|--|
| Dimensions | www.vishay.com/doc?95021 |
|------------|--|



TO-244

DIMENSIONS in millimeters (inches)





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